

# EYANG TECHNOLOGY DEVELOPMENT CO.,LTD

## C0402X7R104K500NTC

High Capacitance Multi-layer Ceramic Chip Capacitor

# **SPECIFICATION**

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### 1. Scope:

This specifications are applicable to the high capacitance multi-layer ceramic chip capacitor (MLCC) .

Type of Dielectrics: X5R;

Chip Size: 0402;

Capacitance range:  $0.1\mu F$ ;

### 2. Part Number System:

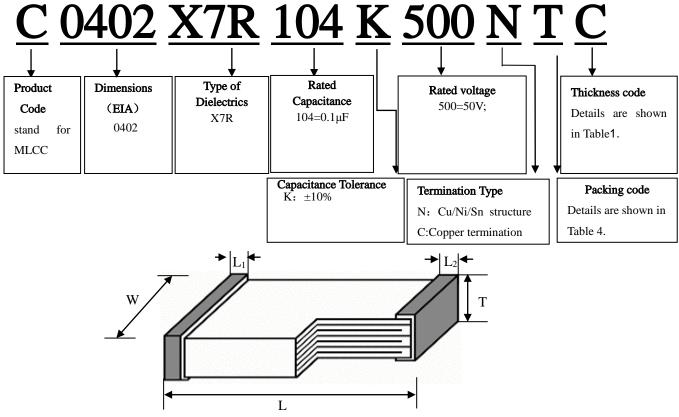


Fig.1 Configuration and Dimension of MLCC

Table 1 Dimension of MLCC (Unite: mm)

Size	Length (L)	Width (W)	Width of Termination $(L_1, L_2)$	Thickness (T)	Thickness code
0402	1.00+0.30-0.05	$0.50^{+0.30}$ -0.05	0.10~0.35	$0.50^{+0.30}$ -0.05	С

### Table 2 Type of dielectrics

Type of Dielectrics	Operating Temperature Range	Temperature Coefficient or Characteristic
X7R	-55°C ∼+125°C	±15%

#### Table 3 Rated Voltage and Rated Capacitance

Size	Rate voltage	Capacitance	Thickness code	
Size	$/U_R$	X5R	Tillexiless code	
0402	50V	0.1μF	С	

### Type of Packing:

Reel Packaging (standard carrier tape disc packaging), every disc smallest package shown in Table 4.



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#### Table 4 Packing type

Chip Size	0402		
Packing code	T	J	
Disc size	7"	13"	
QTY (Kpcs)	10	50	
Carrier Tape type	Paper	Paper	
Thickness code	B/N	B/N	

Firstly, 5 reels in 1 box; Secondly, 12 boxes maximum in 1 carton. Each carton mostly outfit 12 boxes, the remaining gap fill with lightweight complementary material. The packaging can meet customers' special demands.

### 3. Technical specifications and test methods:

### 3.1 Visual Inspection:

**3.1.1 Requirement:** no obvious defects on ceramic body and termination.

**3.1.2 Test Method:** Microscope 10×.

#### 3.2 Size:

**3.2.1 Requirement:** Configuration and dimension of MLCC are shown in Figure 1 and Table 1.

**3.2.2 Test Method:** Measuring by gages which precision is not less than 0.01 mm.

### 3.3 Operating Environment:

X7R	Temperature:	-55°C∼+125°C;	Relative humidity:	≤95% (25°C)	Atmosphere:	86 KPa ∼106KPa	
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### 3.4 Electrical Parameters and Test Methods:

Table 5 Specifications and Test Methods of MLCC Electrical Parameter

No.	Item	Specification	Test Method	
1	Capacitance (C)	Within the specified tolerance	Temperature: 18~28°C; Humidity: ≤RH 80%;	
2	Tangent of Loss Angle/ (tgδ)	$\begin{array}{lll} \textbf{X7R, X5R, X5S, X5T:} \\ U_R \geq & 25V & tg\delta \leq 1000 \times 10^{-4} \\ U_R = & 16V & tg\delta \leq 1250 \times 10^{-4} \\ U_R \leq & 10V & tg\delta \leq 1500 \times 10^{-4} \\ \end{array}$ $\begin{array}{lll} \textbf{Y5V:} \\ U_R \geq & 25V & tg\delta \leq 1000 \times 10^{-4} \\ U_R = & 16V & tg\delta \leq 1500 \times 10^{-4} \\ U_R \leq & 10V & tg\delta \leq 1800 \times 10^{-4} \\ \end{array}$	Test requency: X7R, X5R, Y5V: $100 pF < C \le 10 \mu F$ , $f=1KHz\pm 10\%$ ; $C>10 \mu F$ , $f=100$ or $120Hz$ ; Test Voltage: $100 pF < C \le 10 \mu F$ : $U_R>6.3 V$ $1.0\pm 0.2 V rms$ $U_R\le 6.3 V$ $0.5\pm 0.2 V rms$ ; $C>10 \mu F$ : $0.5\pm 0.2 V rms$	
3	Insulation Resistances/ (Ri)	Ri×C≥100s	Temperature: 18~28°C; Humidity: ≤RH 80%; Rated voltage 60 ± 5S	
4	Withstanding voltage (WV)	No breakdown or flashover during test	2.5×U <sub>R</sub> t=1 minute Charge/discharge current not exceeds 50mA.	

Note: Capacitance test instructions of Class 2 ceramic capacitors

When the capacitor initial capacitance is lower than its tolerance value, the test sample need to be heated for  $60 \pm 5$  minutes at 150 °C  $\pm 10$  °C. Recover it, let sit at room temperature for 24±2 hrs, and then test the capacitance.



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# 3.5 Environment Test Specifications and Methods:

Without specific note, the "test method" in Table 6 is based on GB/T 21041/21042 IDT IEC60384-21/22.

### Table 6 Environment Test Specifications and Methods

No.	Item	Specification		Test Method	
1	Temperature Coefficient of Capacitance $(\alpha_c)$ or Temperature Characteristics	Special preconditioning for 1hr at 150 °C follows 24hrs, The ranges of capacitance change compared with the temperature ranges ( $\theta$ 1, 25 $\theta$ 2) shall be within the specified ranges. <b>X5R</b> , <b>X5S</b> , <b>X5T</b> , <b>Y5V</b> : $\theta_1$ =-55 °C, $\theta$ 2=85 °C <b>X7R</b> : $\theta_1$ =-55 °C, $\theta_2$ =125 °C <b>Test Voltage</b> : $\begin{array}{c ccccccccccccccccccccccccccccccccccc$			
2	Resistance to Soldering Heat	Visual: No visible damage and uncovered shall be less than 25%.  Capacitance Change:  X7R, X5R, X5S: ΔC/C≤±15%;  X5T, Y5V: ΔC/C ≤ ±30%  tgδ and Ri: meet the initial specified the specified specified in the specified specified in the specified s	Special preconditioning for 1hr at 150°C followed by 24hrs; Preheat the capacitor at 110 to 140°C for 30-60s. Immerse the capacitor in an eutectic solder solution at 260±5°C for 10±1 seconds. The depth of immersion is 10mm.Recover it, let sit at room temperature for 6 24±2hrs,then observe appearance and measure electrical characteristics.		
3	Solderability	75% min. coverage of both terminal electrodes is soldered evenly and continuously.		Immerse the test capacitor into a methanol solution containing rosin for 3 to 5 seconds, preheat it at 80 to 140°C for 30s to 60s and immerse it into molten solder of 235±5°C for 2±0.2 seconds. The depth of immersion is 10mm.	



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		Visual: No visible damage.	Solder the capacitor to the test jig (glass epoxy boards) shown in Fig. a. Apply a force in the direction shown in Fig. b. Bending 2mm at a speed of 1mm/sec and hold for 5±1secs, then measure the capacitance.
4	Bond Strength of Termination	Capacitance Change: X7R, X5R: $\Delta C/C \le \pm 10\%$ ; Y5V: $\Delta C/C \le \pm 30\%$	C b 04.5  40 Fig: a  20
5	Adhesion	Visual: No visible damage.	When Soldering the capacitor on a P. C. board, apply a pushing force of 5N for 10±1secs.  F=5N  Capacitor  P. C. Board
		Visual: No visible damage.	Sample shall be mounted on a suitable
6	Vibration	Capacitance Change: X7R, X5R: ΔC/C≤±15%; X5T, Y5V: ΔC/C≤±20%	substrate.  Amplitude: 1.5mm  Frequencies: 10 Hz~100 Hz ~200Hz, and Harmonic vibration of uniform changes, 5 minutes sweep cycle.  Repeat this for 2hrs each in 3
		tgδ and Ri: meet the initial specification in Table 5.	perpendicular directions X, Y, Z, total 6hrs. (Related STD: IEC 68-2-6 test Fc)



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	Rapid change of temperature	Visual: No visible damage.	Special preconditioning for 1hr at 150°C followed by 24hrs.  Fix the capacitor to the supporting jig.  Expose the capacitors in the				
7		Capacitance Change: X7R, X5R, X5S: ΔC/C≤±15%; X5T, Y5V: ΔC/C≤±20%	$\begin{array}{cccccccccccccccccccccccccccccccccccc$				
		tgδ and Ri: meet the initial specification in Table 5.	<b>X7R:</b> $\theta_A = -55^{\circ}\text{C}$ , $\theta_B = 125^{\circ}\text{C}$ ; <b>X5R, X5S, X5T, Y5V:</b> $\theta_A = -55^{\circ}\text{C}$ , $\theta_B = 85^{\circ}\text{C}$ Recover it, let sit at room temperature for $24 \pm 2 \text{hrs}$ , then observe appearance and measure electrical characteristics.				
		Visual: No visible damage.					
	Damp Heat (Steady State)	Capacitance change: X7R, X5R, X5S: ΔC/C≤±12.5%; X5T, Y5V: ΔC/C≤±30%	Special preconditioning for 1hr at 150°C followed by 24hr  Test Temperature: 60°C±2°C				
8		<b>Tgδ:</b> tgδ≤2×The initial index in Table 5	Humidity: RH 90~95%  Duration: 500 hrs				
		Insulation Resistances (Ri): X7R, X5R, X5S, X5T, Y5V: Ri $\geq$ 1000M $\Omega$ or Ri $\times$ C $\geq$ 50s (U <sub>R</sub> $\geq$ 25V), whichever is smaller; Ri $\geq$ 1000M $\Omega$ or Ri $\times$ C $\geq$ 10s (U <sub>R</sub> $\leq$ 16V), whichever is smaller	Recover it, let sit at room temperature for 24±2hrs, then observe appearance and measure electrical characteristics.				
		Visual: No visible damage.	A 1 1000/ of the set I DC				
		Capacitance change: X7R: ΔC/C≤±12.5%; X5R, X5S: ΔC/C≤±15%; Y5V: ΔC/C≤±30%	Apply 100% of the rated DC voltage at 60°C for 1hr. Remove and set for 24hours at room temperature. Perform initial measurement.  Test Temperature: 60±2°C;				
		<b>Tgδ:</b> tgδ≤2×The initial index in Table 5	Humidity: RH 90~95%; Test Voltage: U <sub>R</sub> ;				
9	Damp heat with load	Insulation Resistances (Ri): Ri≥500MΩ or Ri×C≥25s,whichever is smaller;	Duration: 500hrs; Charge/discharge current not exceeds 50mA. Recover it, let sit at room temperature for 24±2hrs, then observe appearance and measure electrical characteristics.				



onditioning for 1hr at wed by 24hrs ature:  ;  X5R, Y5V: 85°C;
ature:
;
<b>₹5R, Y5V:</b> 85°C;
00hrs;
: 1.5×U <sub>R</sub> *
, let sit at room
for 24±2hrs, then
pearance and measure
aracteristics.
2 X5R 105, 0603 X5R
X5R 106, 1206 X5R
for 24±2hrs, pearance and mearacteristics.

voltage is 1.0 ×U<sub>R</sub>

# 4. Packaging, transportation and storage:

### 4.1 Packing:

### 4.1.1Type of packing:

Reel Packaging (standard carrier tape disc packaging), single disc smallest package are shown in Table 4.

### 4.1.2 Carrier Tape Dimensions:

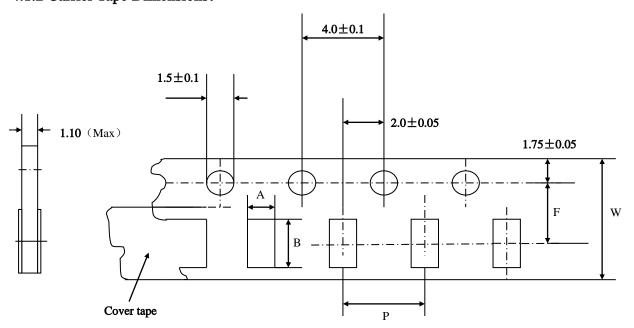


Figure 2 Carrier



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### Table 7 Carrier size

	Size of product		
Mark	0402		
	Size (Unit: mm)		
A ( Width of the square hole )	0.70±0.10		
B ( Length of the square hole )	1.20±0.10		
F (Center distance between			
positioning hole and square	3.50±0.05		
hole )			
P ( Square hole spacing )	2.00±0.10		
W (Width of carrier)	8.00±0.20		

### 4.1.3 Disc Size:

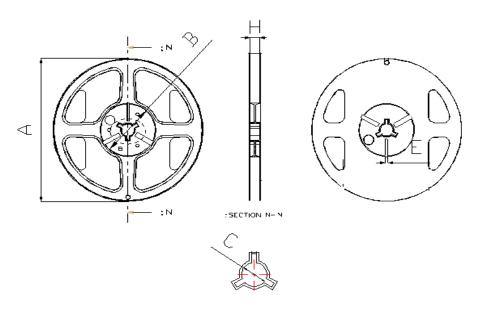


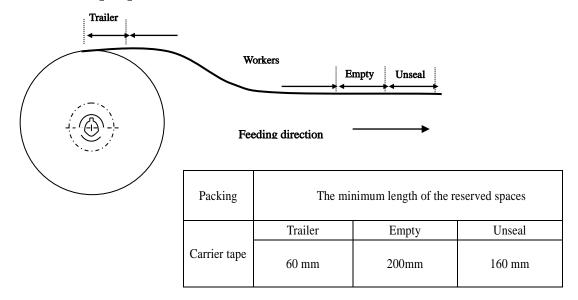
Figure 3 disc

### Table 8 Disc Size

圆盘尺寸	A/mm	B/mm	C/mm	E/mm	H/mm
7"	Φ178±2.0	Ф60±2.0	Φ13±1.0	4±1.0	9.5±1.0
13"	Ф330±2.0	Φ100±2.0	Φ13±1.0	3±1.0	10±1.0



### 4.1.4 Carrier Tape Specifications:



### 4.1.5 Performance of Carrier Taping::

#### 4.1.5.1 Strength of Carrier Tape and Top Cover Tape:

#### a. Carrier Tape

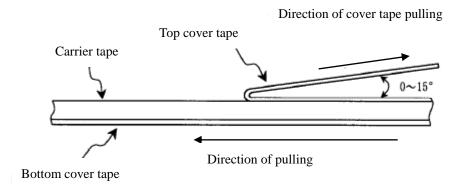
When a tensile force 1.02kgf is applied in the direction to unreel the tape, the tape shall withstand this force.

### b. Top cover Tape

When a tensile force 1.02kgf is applied to the tape, the tape shall withstand this force.

### 4.1.5.2 Peeling Strength of Top Cover Tape:

Unless otherwise specified, the peeling strength of top cover tape shall be within 10.2 to 71.4 gf when the top cover tape is pulled at a speed of 300mm/min with the angle of 0 to  $15^{\circ}$  (see the following figure).



### 4.2 Shipment:

It must not be got rain, snow, and must avoid erosion of acid and alkali during the course of shipment.

### 4.3 Storage:

#### Period of Store:

12 months, otherwise, its solderability must be inspected again.

#### Condition of Store:

Temperature: Below 35°C Humidity: Below RH70%.